



Capabilities

Design & Manufacturing

Aerospace Semiconductor's commercial aviation, space, defense and mining markets demand a broad range of capabilities to successfully deliver semiconductor circuit solutions reliably to our valued customers. We are fully capable of a turnkey design and manufacturing of high performance circuits for a variety of substrates, packages and using assembly techniques all aimed at providing our customers with the performance they demand.

Our in-house capabilities include:

Electrical Testing

DC & AC Testing

Temperature Testing

Data Recording

Sealing

Vacuum solder seal oven

Seam Seal

Cap Welding

Ceramic Lid/Epoxy

Glob Top

Substrates

Thick Film – Alumina, BeO, AlN

Thin Film – Alumina, BeO

Direct Bond Copper

Polyimide, G10, Flex

Design and Manufacturing

Chip & Wire Hybrids

Multi Chip Modules

Surface Mount Hybrids

Chip On Board

Power Hybrids

Custom Packaging

Legacy Components

Assembly

Die Attachment; Epoxy, Solder, Eutectic

Wirebonding; Gold & Aluminum Ball Wedge, 1 to 20 mils wires, high speed automated bonder

Surface Mount

Plastic encapsulation/over-mold

Screening

Constant Acceleration

Temperature Cycling

Hermetic; Fine and Gross Leak Check Burn In

From testing to design to screening and more, if you need semiconductors appropriate for harsh operating environments, we've got the ability to supply them. Contact us today to find the perfect solution for your needs.



Our Top Markets

- Commercial Aviation
- Space
- Defense
- Mining

Our Main Services:

- Hybrid Microcircuit
- Obsolete Semiconductors
- Semiconductor Packaging – Standard and Custom

Quality Certification



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